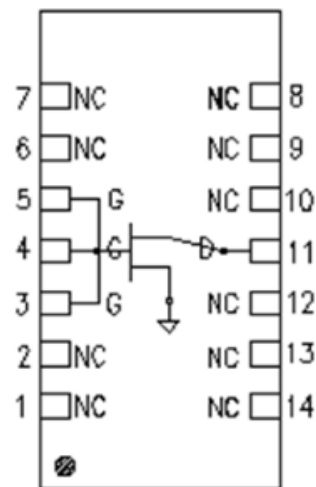




15 Watts • 50 Volts

30 - 3500 MHz Broadband Transistor



TYPICAL AVIONICS BAND CW PERFORMANCE DATA – V_{dd}=50V

Frequency	P _{OUT} (W)	IRL (dB)	η_D (%)	G _P (dB)	Droop (dB)
960 MHz	17	-15.6	65.0	17.5	-
1090 MHz	18	-9.2	67.0	18	-
1215 MHz	18	-10.0	69.9	17	-

TYPICAL WIDE BAND CW PERFORMANCE DATA – V_{dd}=50V

Parameter	30MHz	1GHz	2.5GHz	3.5GHz	Units
Gain	25	23	17	16	dB
Psat	19	19	17	15	W
G _p at Psat	22	19	15	14	dB
PAE at Psat	75	69	60	60	%

CORRECT BIAS SEQUENCING**Turning the device ON**

1. Set V_{GS} to the pinch-off (V_P), typically -5 V.
2. Turn on V_{DS} to nominal voltage (50 V).
3. Increase V_{GS} until the I_{DS} current is reached.
4. Apply RF power to desired level.

Turning the device OFF

1. Turn the RF power off.
2. Decrease V_{GS} down to V_P.
3. Decrease V_{DS} down to 0 V.
4. Turn off V_{GS}

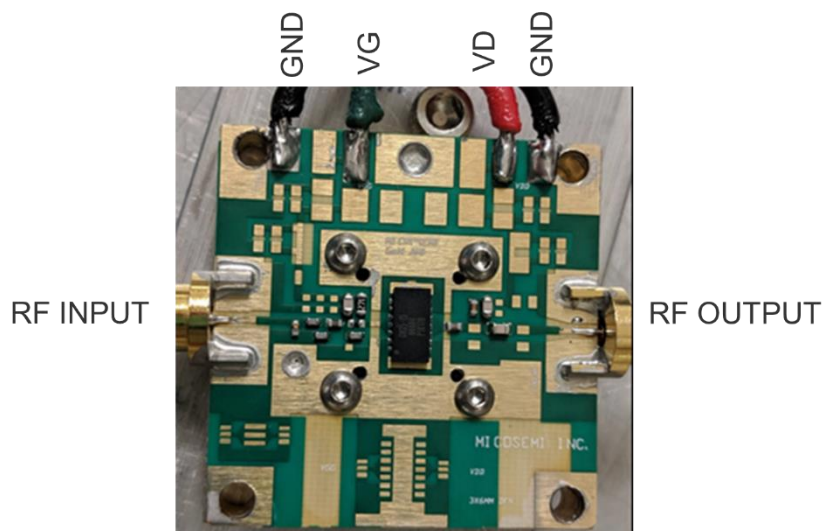
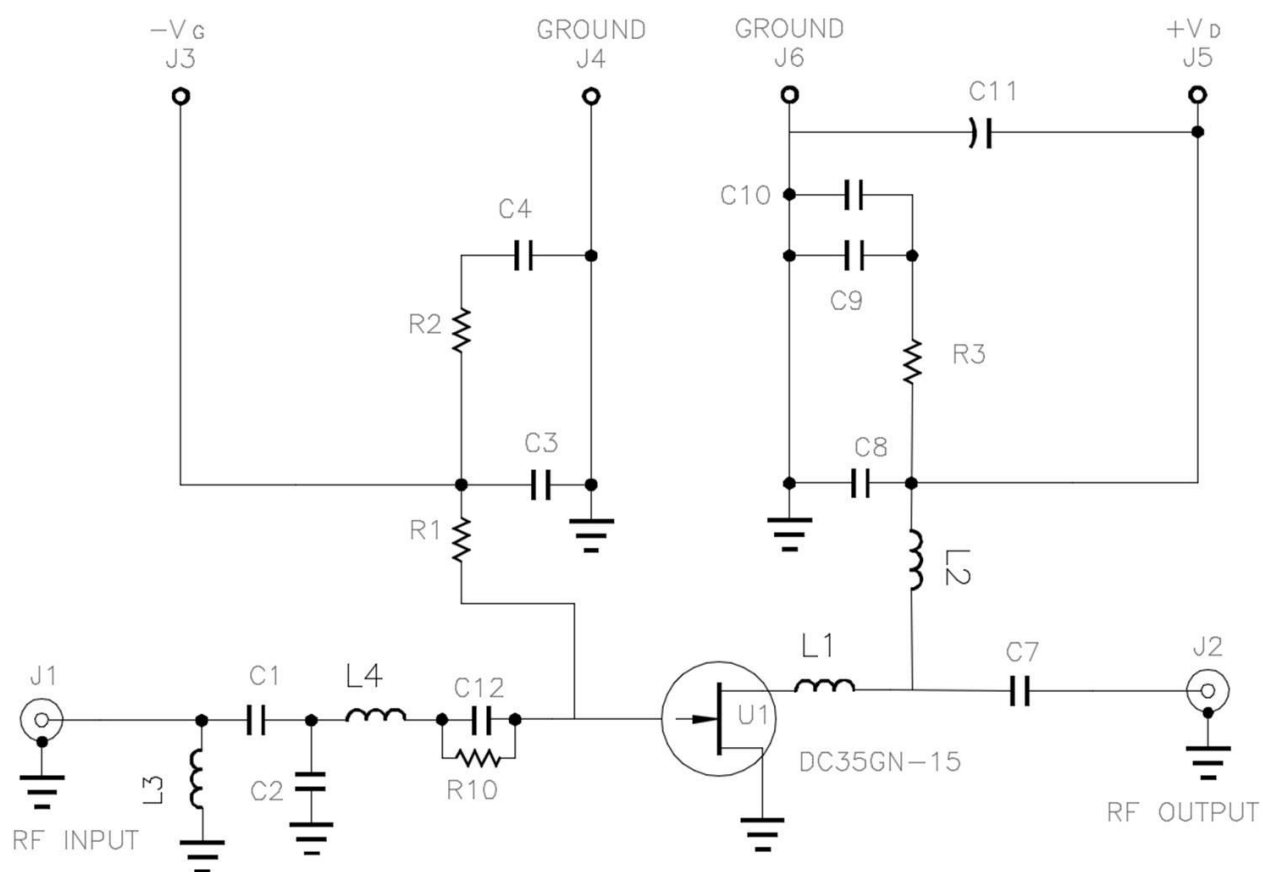


PRELIMINARY

DC35GN-15-D3

15 Watts • 50 Volts
30 - 3500 MHz Broadband Transistor

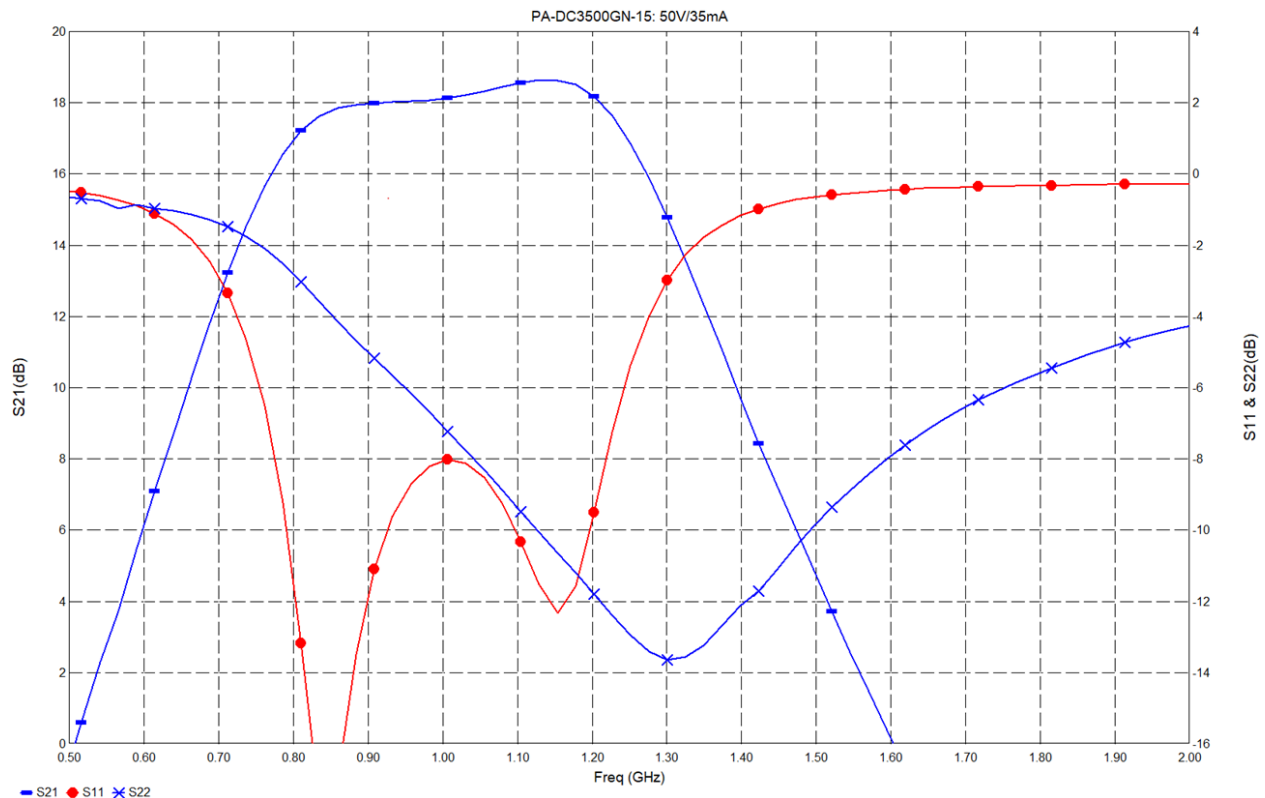
EVALUATION BOARD MATCHING SCHEMATIC INFORMATION 960-1215MHz



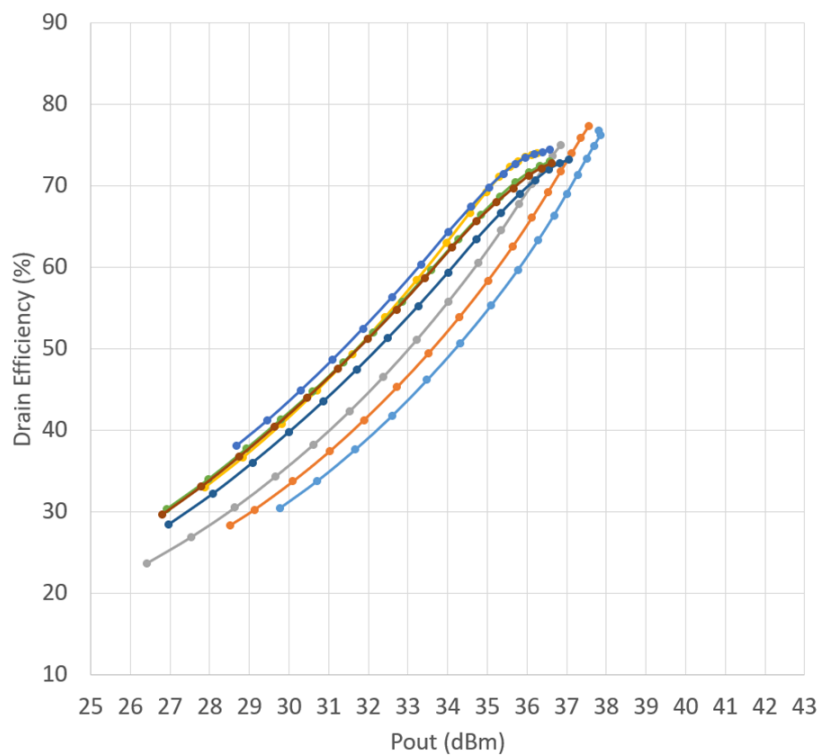
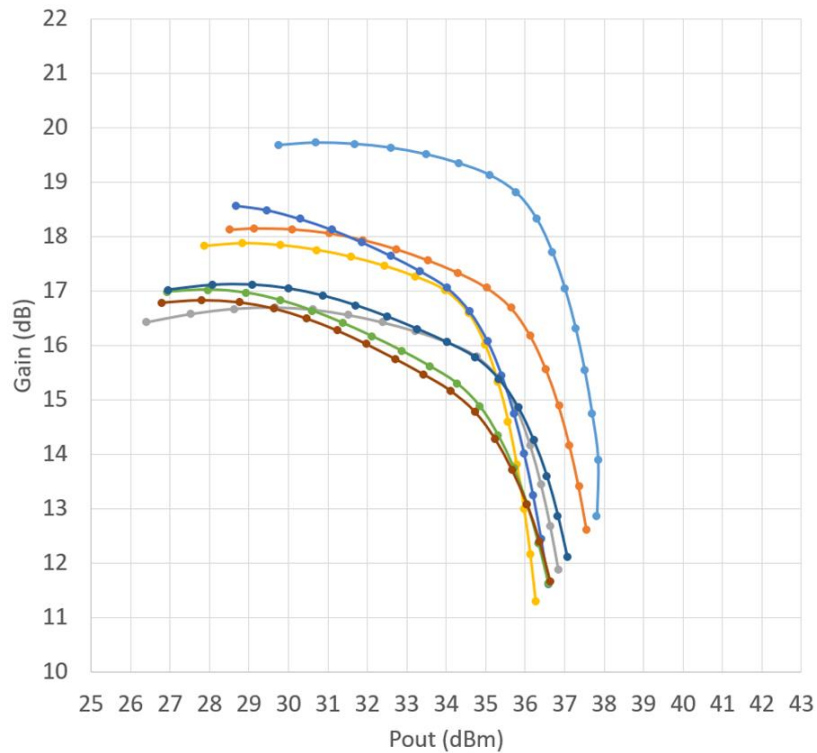
TRANSISTOR MATCHING SCHEMATIC INFORMATION – 960-1215MHz

Ref Des	Value	Description	Manufacturer	Part Number
U1	-	15W GaN discrete PA in 3x6mm DFN	Microchip	DC35GN-15-D3
J1, J2	-	SMA connector		1521-60102
L1	1.8 nH	Inductor, 1A, 0402	Coilcraft	0402CS-1N8XGE
L2	5.1 nH	Inductor, 0.8A, 2%, 0402	Coilcraft	0402CS-5N1XGLU
L3	4.3 nH	Inductor, 1.6A, 2%, 0402	Coilcraft	0402HP-4N3XGLU
L4	2 nH	Inductor, 1A, 2%, 0402	Coilcraft	0402CS-2N0XGLU
C1	5.6 pF	Capacitor, 200V, 5%, 0402	PPI	0402N5R6BW201
C2	6.8 pF	Capacitor, 200V, 5%, 0402	PPI	0402N6R8BW201
C12	12 pF	Capacitor, 200V, 5%, 0402	PPI	0402N120JW201
C3, C8	82 pF	Capacitor, 250V, 5%, 0603	PPI	0603N820JW251
C7	39 pF	Capacitor, 250V, 5%, 0603	PPI	0603N390JW251
R1	270 Ohm	Resistor, 5%, 1/10 W, 0603	Panasonic	ERJ-3GEYJ271V
R10	10 Ohm	Resistor, 1%, 1/20 W, 0201	Yageo	RC0201FR-0710R

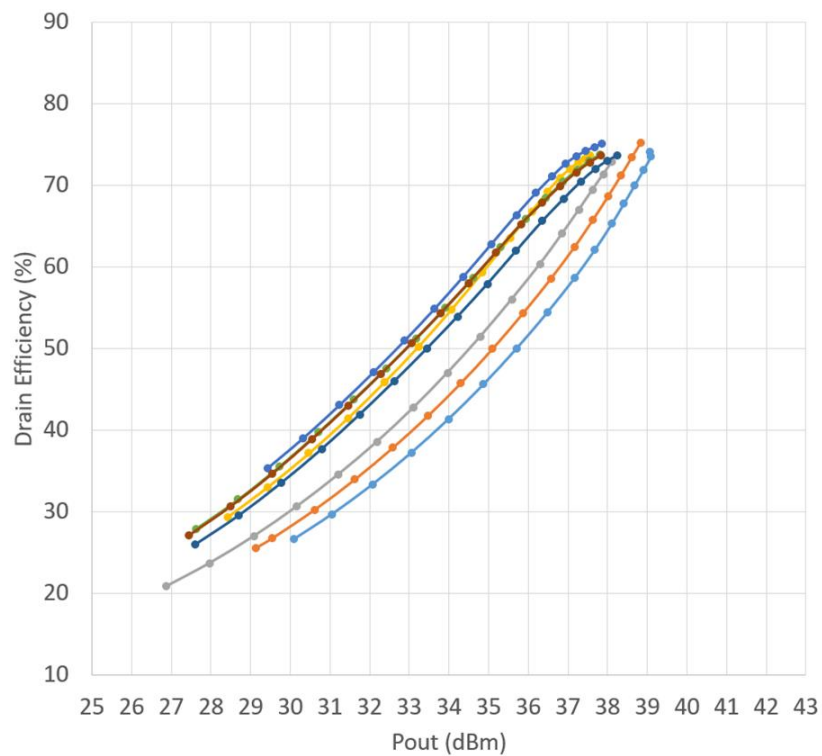
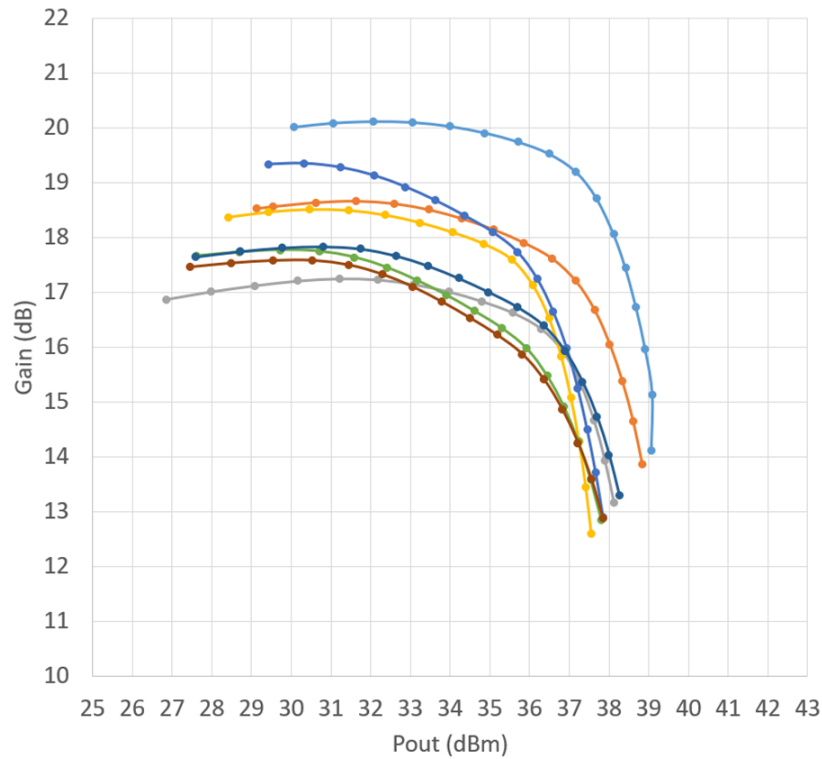
Parts Measured on evaluation board – 12mil thick – RO4350. Electrical and Thermal Gd is provided using copper filled via hole array and evaluation board is mounted to a heat sink.



PERFORMANCE INFORMATION – 960-1215MHz – Vdd=24V, Idq= 10mA



PERFORMANCE INFORMATION – 960-1215MHz – V_{dd}=24V, I_{dq}= 10mA



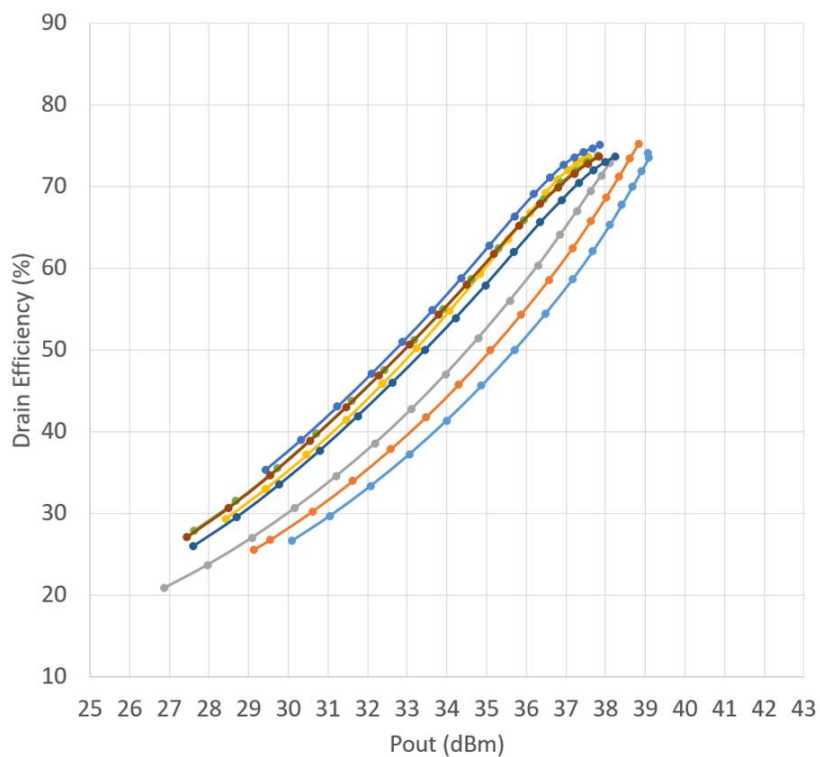
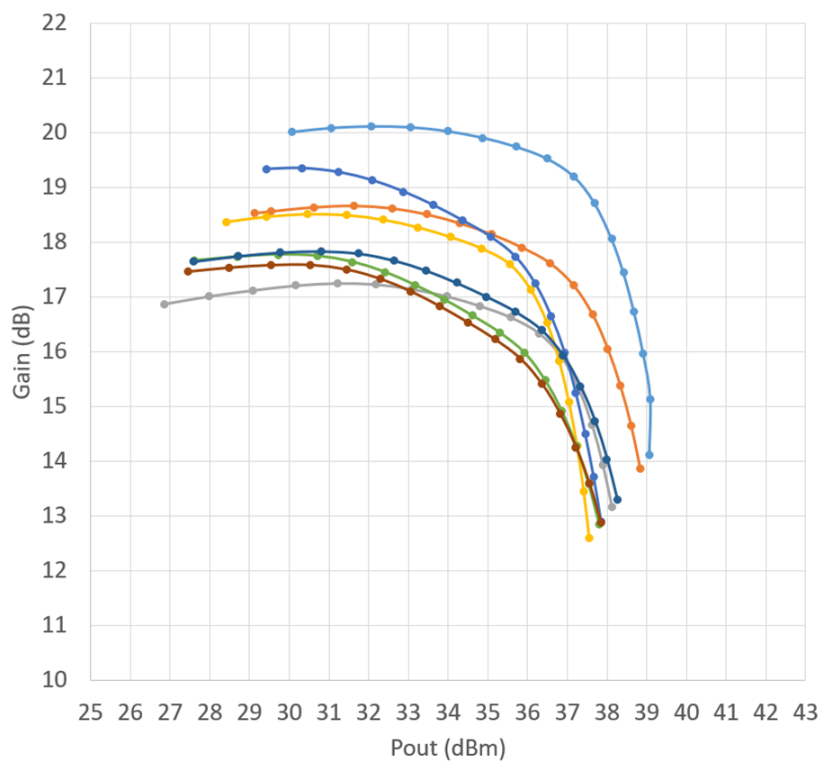


PRELIMINARY

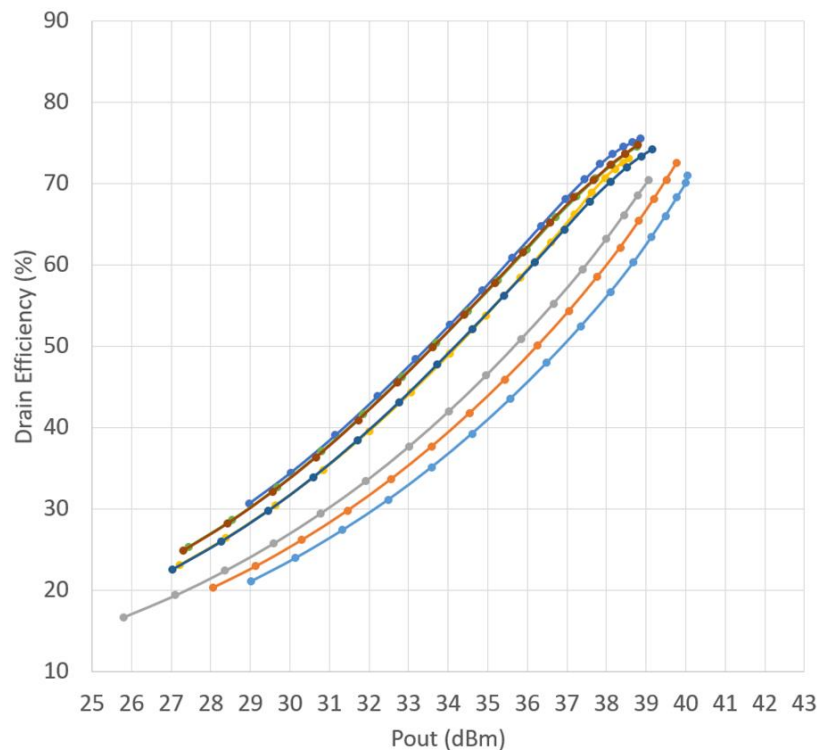
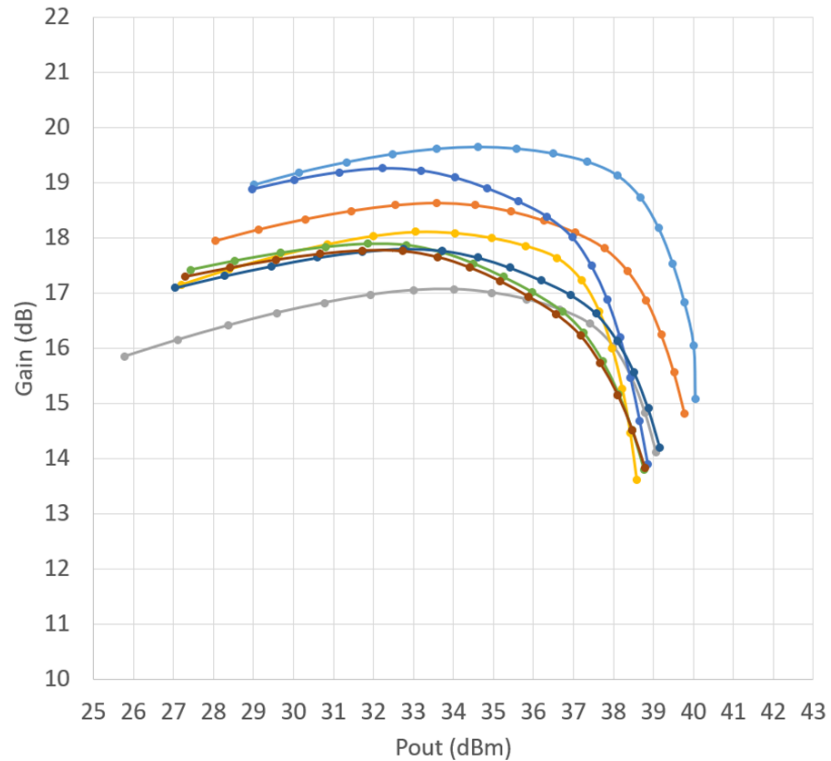
DC35GN-15-D3

15 Watts • 50 Volts
30 - 3500 MHz Broadband Transistor

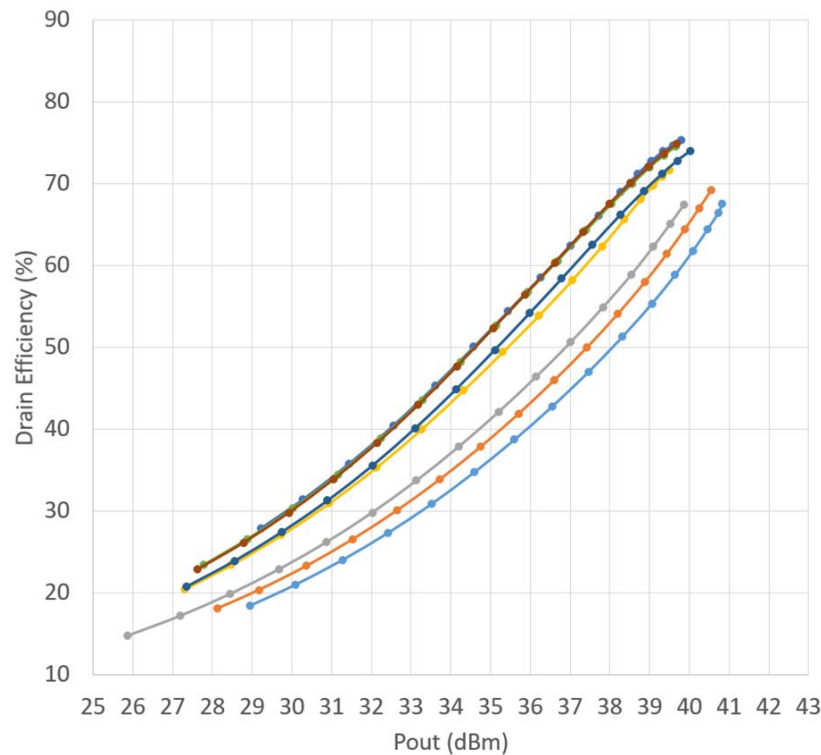
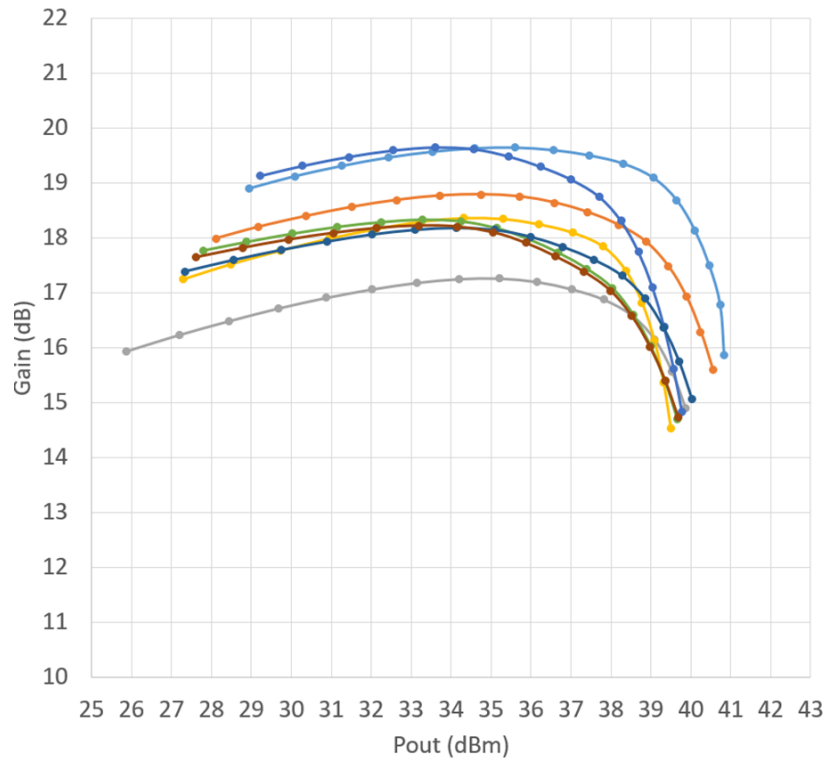
PERFORMANCE INFORMATION – 960-1215MHz – $V_{dd}=28V$, $I_{dq}=10mA$



PERFORMANCE INFORMATION – 960-1215MHz – $V_{dd}=32V$, $I_{dq}=10mA$



PERFORMANCE INFORMATION – 960-1215MHz – $V_{dd}=36V$, $I_{dq}=10mA$



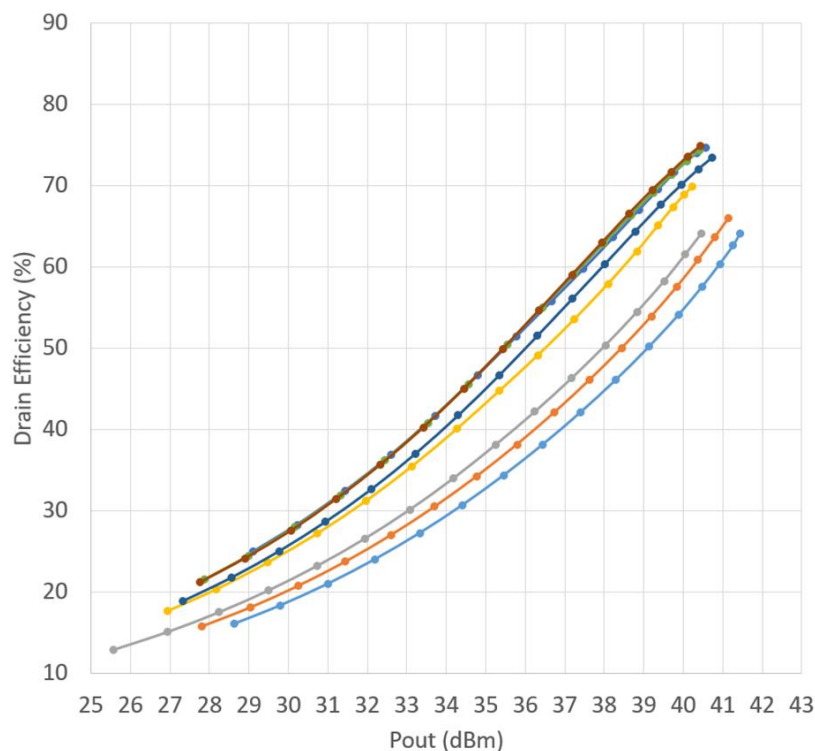
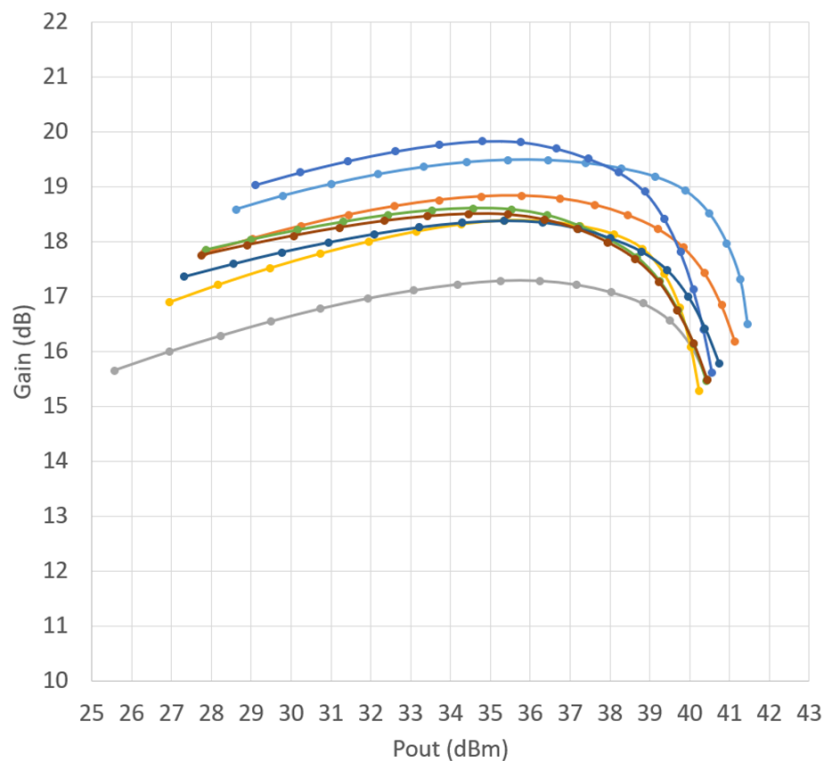


PRELIMINARY

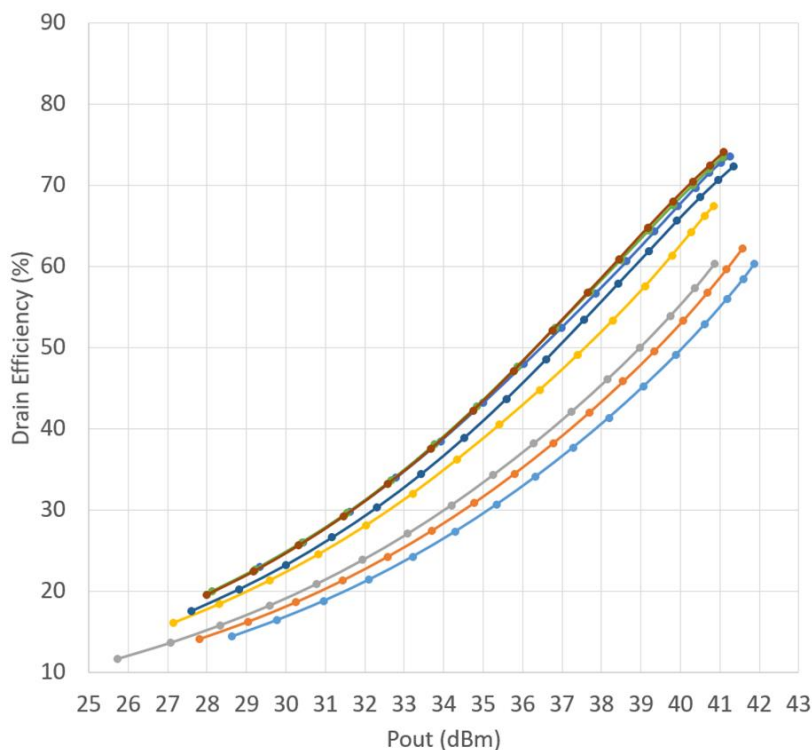
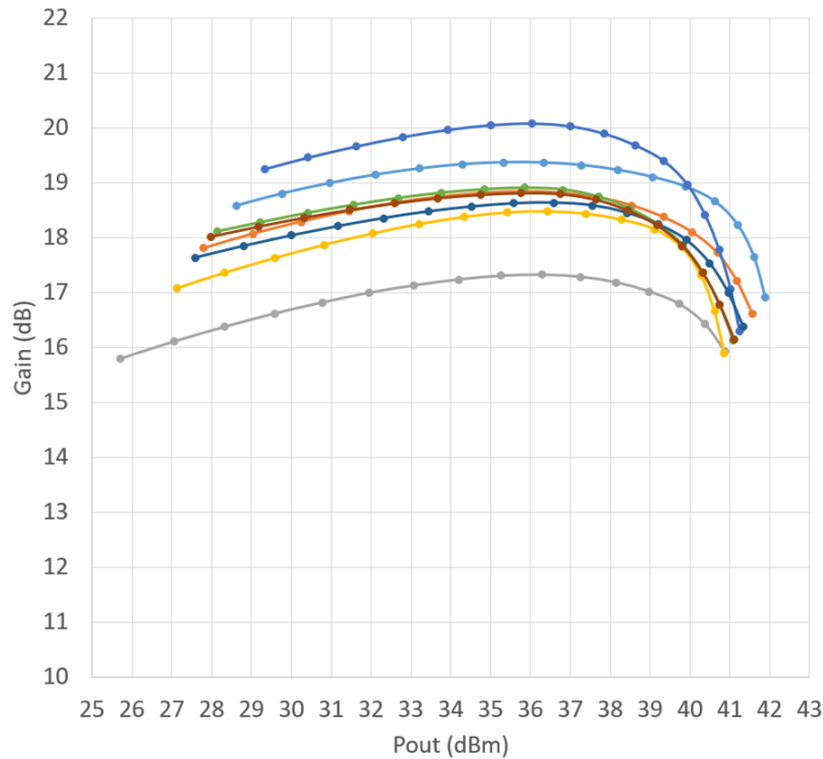
DC35GN-15-D3

15 Watts • 50 Volts
30 - 3500 MHz Broadband Transistor

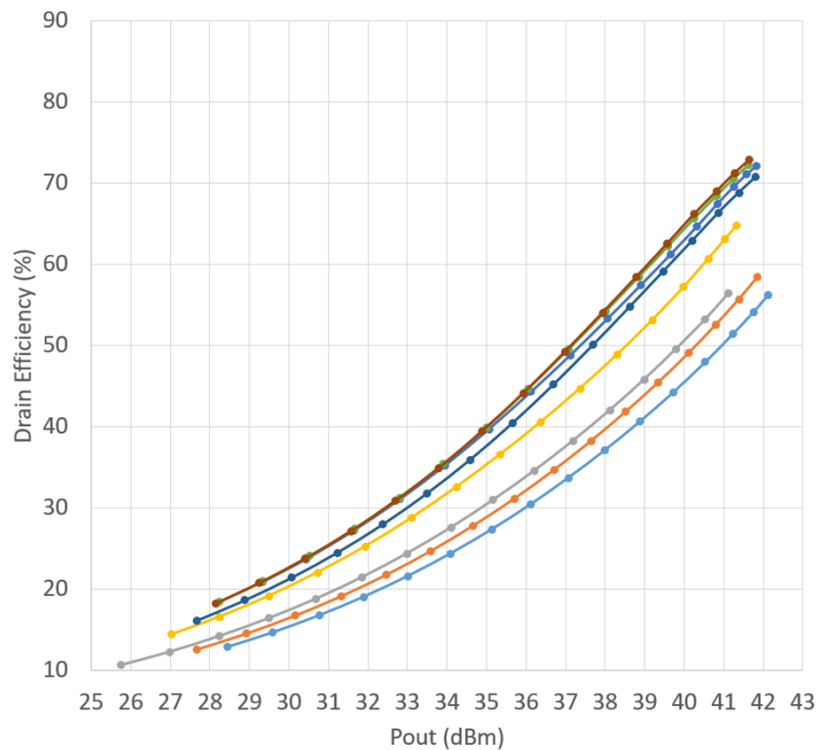
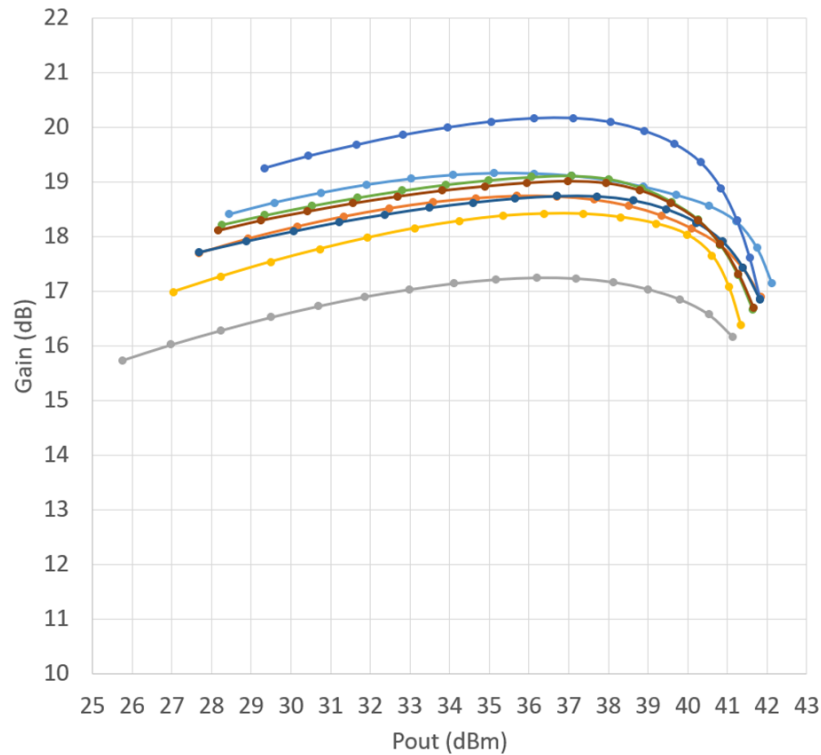
PERFORMANCE INFORMATION – 960-1215MHz – $V_{dd}=40V$, $I_{dq}=10mA$



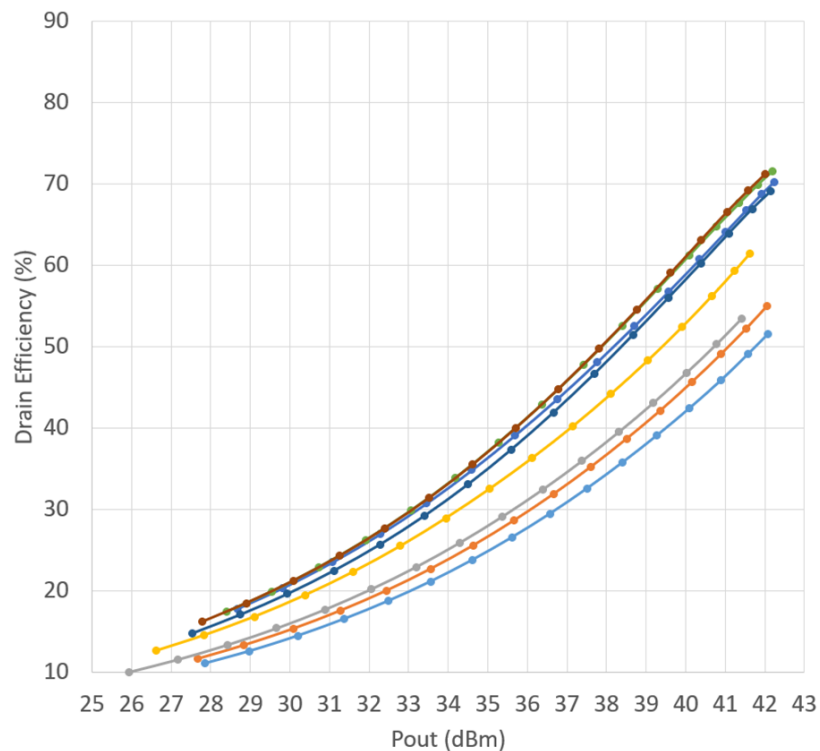
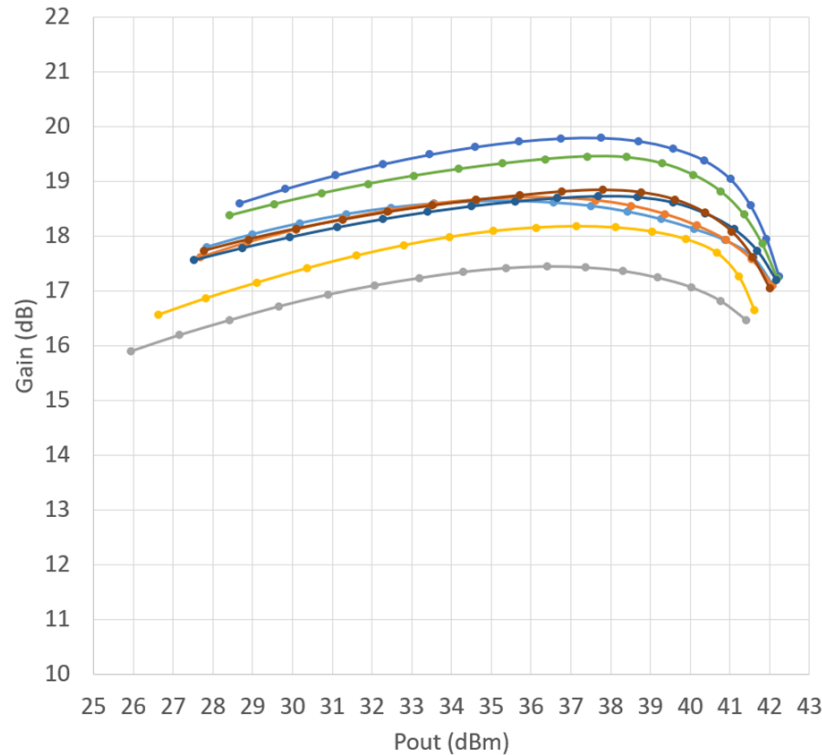
PERFORMANCE INFORMATION – 960-1215MHz – $V_{dd}=44V$, $I_{dq}=10mA$



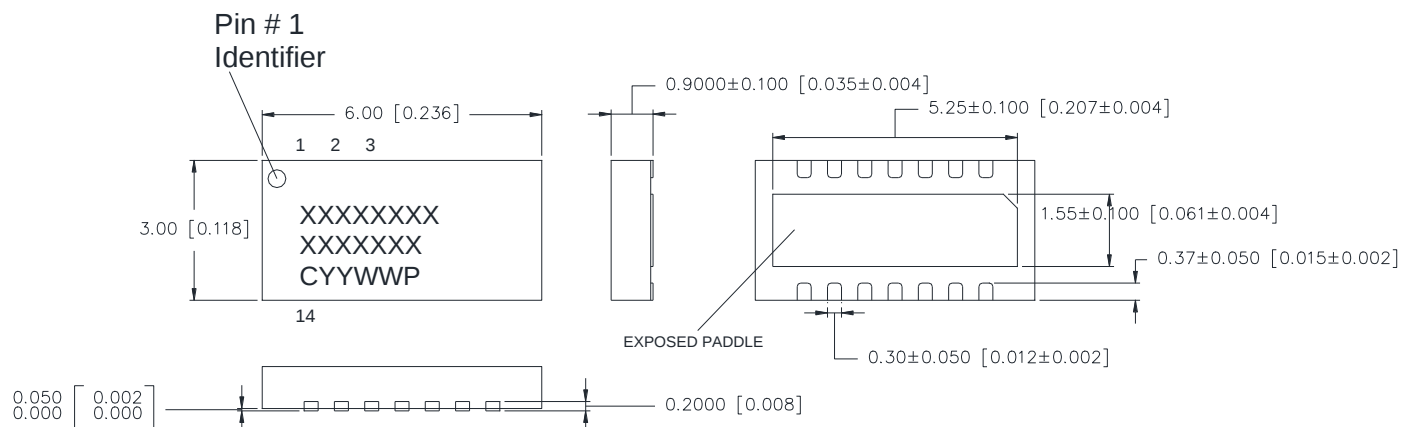
PERFORMANCE INFORMATION – 960-1215MHz – $V_{dd}=48V$, $I_{dq}=10mA$



PERFORMANCE INFORMATION – 960-1215MHz – $V_{dd}=52V$, $I_{dq}=10mA$



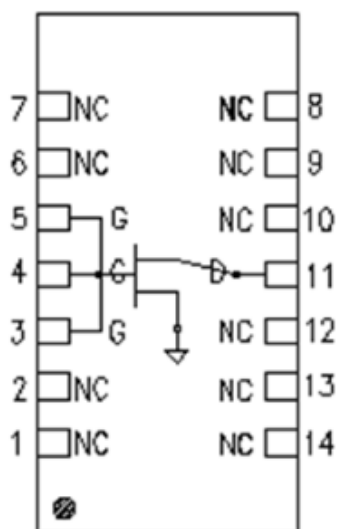
Lead Free 3x6mm 14-LD DFN - PACKAGE DIMENSION



MARKINGS:
XXXXXXXXXX = Part No
XXXXXXXXXX = Wafer Lot No
C=Country of Origin, YYWW = Date Code, P=Plating

Notes:
1. Reference package outline drawing for additional dimensional and tolerance information
2. All dimensions shown as mm/in

Pin Configuration



Pin No.	Function	Pin No.	Function
1	No Connection	8	No Connection
2	No Connection	9	No Connection
3	V_{GG}/RF_{IN}	10	No Connection
4	V_{GG}/RF_{IN}	11	V_{DD}/RF_{OUT}
5	V_{GG}/RF_{IN}	12	No Connection
6	No Connection	13	No Connection
7	No Connection	14	No Connection
	RF/DC GND	15	Paddle

Handling Procedures

Please observe the following precautions to avoid damage

Static Sensitivity

GaN Devices and Circuits are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these Class 1B devices

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Revision History

Revision Level / Date	Para. Affected	Description
07 Oct 2019	-	Preliminary Release